

[illegible]

A power lead and a ground lead are connected to corresponding pads of a die through an intra-package wiring substrate. A ground plane is formed in a mold under the intra-package wiring substrate extending along the bottom surface of the mold, and connected to the ground lead. A decoupling capacitor is connected to power wiring and the ground plane to prevent EMI caused by switching noise current generated by the power circuit of the die.

## Figures

Figure 1: A diagram illustrating the relationship between the variables  $x$ ,  $y$ , and  $z$ . The diagram shows a set of axes with  $x$  and  $y$  as the primary dimensions, and  $z$  as a derived dimension. The axes are labeled with their respective variables, and the origin is marked with a small circle. The diagram is a simple line drawing with no numerical values or specific data points.